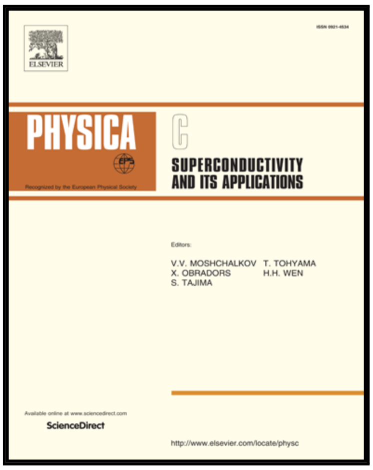

Study on Reducing the Charge Delay of the No-insulation HTS Coil after Solder Impregnation

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PII: S0921-4534(18)30054-6
DOI: 10.1016/j.physc.2018.06.004
Reference: PHYSC 1253370

To appear in: *Physica C: Superconductivity and its applications*

Received date: 29 January 2018
Revised date: 18 May 2018
Accepted date: 3 June 2018

Please cite this article as: Y.Q. Li , J.W. Zhang , Z.Y. Li , Z. Hong , Z. Jin , Study on Reducing the Charge Delay of the No-insulation HTS Coil after Solder Impregnation, *Physica C: Superconductivity and its applications* (2018), doi: 10.1016/j.physc.2018.06.004

Highlights

- A new impregnation method is proposed for NI coils using conductive material, solder.
- PI control method to reduce the charge delay of the solder impregnated HTS coil.
- The basic theory of the PI control is introduced.
- The experiments and simulations are compared.